

Final Product/Process Change Notification

202211009F01

Dear Tracy Hoglin,

Issue Date: 02/12/2022

Effective Date: 01/05/2023

Here is your personalized quality information concerning products our customers and partners purchased from Ampleon.

For detailed information we invite you to [view this notification online](#)

Management Summary

The soft solder die bond process for High Aspect Ratio die sizes is replaced by a RoHS compliant lead free Silver sinter die bond process.

Change Category

<input type="checkbox"/> Wafer Fab process	<input type="checkbox"/> Assembly Process	<input type="checkbox"/> Product Marking	<input type="checkbox"/> Design
<input type="checkbox"/> Wafer Fab materials	<input checked="" type="checkbox"/> Assembly Materials	<input type="checkbox"/> Electrical spec./Test coverage	<input type="checkbox"/> Mechanical Specification
<input type="checkbox"/> Wafer Fab location	<input type="checkbox"/> Assembly Location	<input type="checkbox"/> Test Location	<input type="checkbox"/> Packing/Shipping/Labeling

Introduction of Silver sinter die attach technology in OMP780 package Phase2

Information Notification

The soft solder die bond process is replaced by a lead free Silver sinter die bond process. For details see the presentation available in the ePCN tool. Phase 1 include non-High Aspect Ratio die sizes.

Why do we implement this change?

The Silver sinter die attach process is introduced to make products in OMP780 packages RoHS compliant, standardize the assembly process with other OMP platforms, improve void control, reduce risk on die cracks and lower and tighten the Rth distribution.

Identification of affected Products

Top side marking

RHF code on product marking and packing labels will change from H (exempted lead and Halogen free) to D (Lead free and Halogen free)

Product availability

Sample information

Samples are available upon request

Production

Planned first shipment

15/05/2023

Impact

Improve void control to lower and tighten the Rth distribution. RHF code on product marking and packing labels will change from H (exempted lead and Halogen free) to D (Lead free and Halogen free)

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

Existing inventory will be shipped until depleted.

Timing and Logistics

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 2023-01-01.

Additional information

Affected products, sales history information as well as self qualification / additional documents can be accessed here: [view online](#)

Remarks**Contact and Support**

For all inquiries regarding the ePCN tool application or access issues, please contact [Ampleon "Quality Support Team"](#).

For all Quality Notification content inquiries, please contact your local Ampleon Sales Support team.

At Ampleon we are dedicated to creating optimal value for our customers.

Ampleon Quality Management Team.

About Ampleon

Created in 2015, Ampleon is shaped by 50 years of RF power leadership and is set to exploit the full potential of data and energy transfer in RF. Ampleon has more than 1,250 employees worldwide, dedicated to creating optimal value for customers. Its innovative, yet consistent portfolio offers products and solutions for a wide range of applications, such as cellular base stations, radio/TV/broadcasting, radar, air traffic control, cooking, lighting, industrial lasers and medical. For details on the leading global partner in RF Power, visit www.ampleon.com.

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12NC - Changed Product	Customer Part Number	Part Number - Changed Product
9.3496E+11	9.3496E+11	BLP9H10S-500AWT
9.3496E+11	9.3496E+11	BLP9H10S-350A